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(54) SEMICONDUCTOR DEVICE

(57) Abstract:

PURPOSE: To provide a semiconductor device capable of performing a normal operation without being affected by noise in power wirings or the like.

CONSTITUTION: A power pad 52 for a high potential side power supply, a power pad 53 for a low potential side power supply (a grounding side) and power wirings 54 and 55 are formed on a semiconductor substrate 51. The wirings 54 and 55 feed a power supply to each group 56 of circuits, which is constituted of a memory well array, a decoder and the like. The wirings 54 and 55 are wired to the right end part (α) (the left end part β) of a part, in which each group 56 of circuits is arranged, without being connected to the groups 56 of circuits. The wiring 54 is connected to the groups 56 of circuits in order from the group 56 of circuits situated at a position near the pad 52 and the wiring 55 is connected to the groups 56 of circuits in order from the group 56 of circuits at a position far from the pad 53. As a result, a voltage drop in the wiring 54 and a voltage build-up in the wiring 55 run counter to each other and a potential difference between potentials in the wirings 54 and 55 as seen from each group 56 of circuits becomes roughly uniform rgardless of the positions of the groups 56 of circuits to the pads 52 and 53.